

3-647334-1 ✓ ACTIVE

AMP-IN

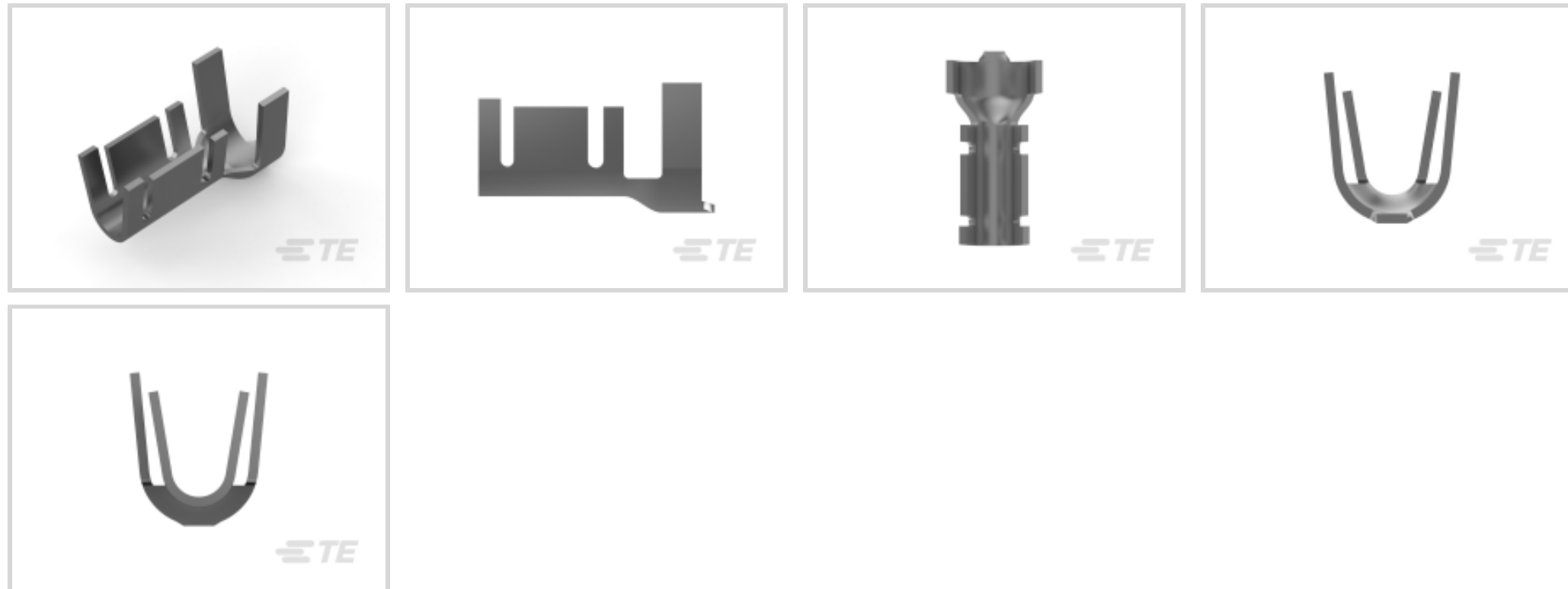
TE Internal #: 3-647334-1

PCB Pin, PCB Hole Diameter 3.18 mm [.125 in], 18 – 14 AWG Wire Size, .8 – 2 mm² Wire Size, Through Hole - Solder, Tin Plating, Box, PCB Terminals

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Terminals & Splices > PCB Terminals



PCB Terminal Type: **PCB Pin**

PCB Thickness (Recommended): **1.57 mm [.062 in]**

PCB Hole Diameter: **3.18 mm [.125 in]**

Profile Height from PCB: **4.7 mm [.187 in]**

Compatible Insulation Diameter (Max): **3.81 mm [.15 in]**

Features

Product Type Features

Terminal Features	Stud Hole
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Usage Conditions

Insulation Option	Uninsulated
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]

Packaging Features

Packaging Quantity	3000
Packaging Method	Box

Dimensions

Extension Below Board	3.18 mm[.125 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
PCB Hole Diameter	3.18 mm[.125 in]
Profile Height from PCB	4.7 mm[.187 in]
Compatible Insulation Diameter (Max)	3.81 mm[.15 in]
Compatible Insulation Diameter Range	2.29 – 3.81 mm[.09 – .15 in]



Wire Size	.8 – 2 mm ²
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Contact Features

Terminal Plating Finish	Bright
Contact Mating Area Plating Material Thickness	5.08 μm[200 μin]
PCB Terminal Type	PCB Pin
Terminal Plating Material	Tin
Terminal Size	Miniature
Terminal Orientation	Straight

Termination Features

Termination Method to PCB	Through Hole - Solder
Product Terminates To	Printed Circuit Board

Mechanical Attachment

Wire Insulation Support	With
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Other

EU RoHS Compliance	Compliant
EU ELV Compliance	Compliant

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

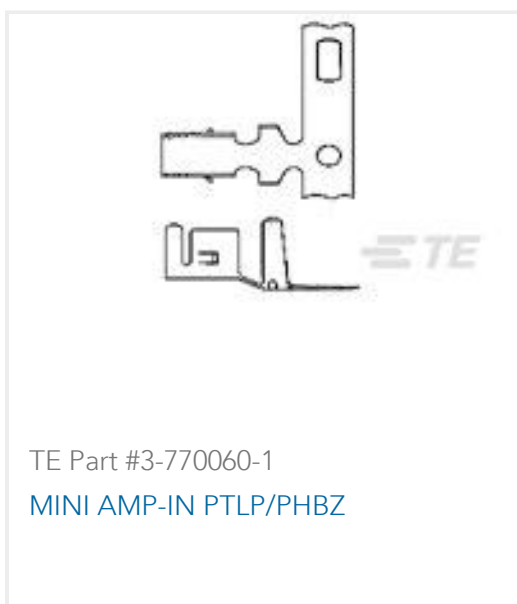
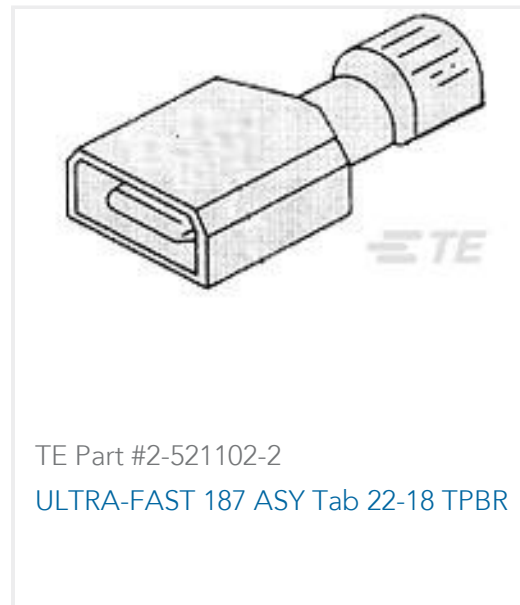
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent

chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought



Documents



Product Drawings

MINI AMP-IN 2000,14-18 AWG LF

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_3-647334-1_B.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_3-647334-1_B.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_3-647334-1_B.3d_stp.zip](#)

English

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Product Specifications

Application Specification

English

Application Specification

English